





#### 240V P-CHANNEL ENHANCEMENT MODE VERTICAL DMOS FET

#### **Features**

- $BV_{DSS} > -240V$
- $R_{DS(on)} \le 8.8\Omega$  @  $V_{GS} = -3.5V$
- Low threshold and Fast switching
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP capable (Note 4)

#### **Mechanical Data**

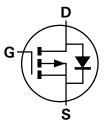
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish @3
- Weight: 0.052 grams (approximate)

### **Application**

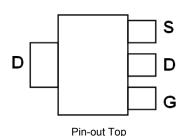
- Electronic hook switches
- Telecoms and Battery powered equipment







Device symbol



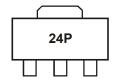
#### Ordering Information (Notes 4 & 5)

Product	Compliance	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZVP4424ZTA	AEC-Q101	24P	7	12	1,000
ZVP4424ZQTA	Automotive	24P	7	12	1,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified.
- 5. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**



24P = Product type Marking Code

**ZVP4424Z** 1 of 6 December 2012 Document Number DS33410 Rev. 2 - 2 © Diodes Incorporated



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	-240	V
Gate-Source Voltage	$V_{GSS}$	±40	V
Continuous Drain Current	I <sub>D</sub>	-200	mA
Pulsed Drain Current (Note 8)	I <sub>DM</sub>	-1.0	A

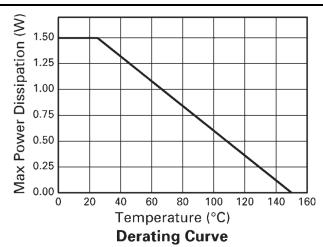
### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

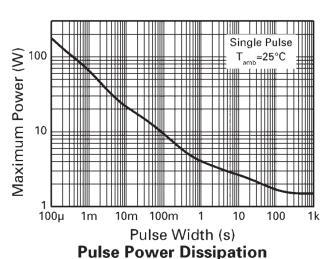
Characteristic	Symbol	Value	Unit	
Power Dissipation	(Note 6)		1.5	W
	(Note 7)	P <sub>D</sub>	2.6	W
Thermal Resistance, Junction to Ambient	(Note 6)	J	83.3	°C/W
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	47.4	°C/W
Thermal Resistance, Junction to Leads (Note 9)		$R_{\theta JL}$	3.64	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

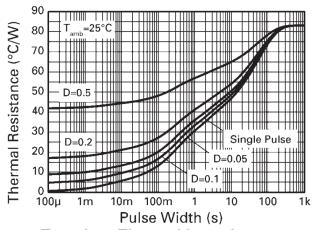
Notes:

- 6. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions.
- 7. For a device surface mounted on FR4 PCB measured at t ≤ 10 sec.
  8. Repetitive rating 25mm x 25mm FR4 PCB, D = 0.02, pulse width 300µs pulse width limited by maximum junction temperature.
- 9. Thermal resistance from junction to solder-point (at the end of the drain lead).

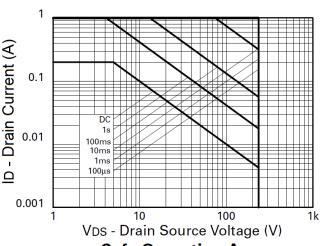
### Thermal Characteristics







## **Transient Thermal Impedance**



Safe Operating Area





# Electrical Characteristics @TA = 25°C unless otherwise specified

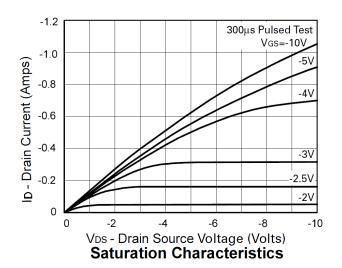
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-240	_	_	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-10	μΑ	V <sub>DS</sub> = -240V, V <sub>GS</sub> = 0V
Zero Gate Voltage Drain Current				-100	μΑ	$V_{DS} = -190V$ , $V_{GS} = 0V$ , $T_A = +125$ °C
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 40V$ , $V_{DS} = 0V$
ON CHARACTERISTICS	ON CHARACTERISTICS					
On state Drain Current (Note 10)	I <sub>D(on)</sub>	-0.75	-1.0	_	Α	$V_{DS} = -10V, V_{GS} = -10V$
Gate Threshold Voltage	V <sub>GS(th)</sub>	-0.7	-1.4	-2.0	V	$I_D = -1 \text{mA}, V_{DS} = V_{GS}$
Static Drain-Source On-Resistance (Note 10)	D	n) —	7.1	9	Ω	$V_{GS} = -10V, I_D = -200mA$
Static Diain-Source On-Nesistance (Note 10)	R <sub>DS(on)</sub>		8.8	11		$V_{GS} = -3.5V$ , $I_{D} = -100mA$
Forward Transconductance (Notes 10 & 12)	9 <sub>fs</sub>	125	_	_	mS	$V_{DS} = -10V, I_{D} = -200mA$
DYNAMIC CHARACTERISTICS (Note 12)						
Input Capacitance	C <sub>iss</sub>		100	200		V <sub>DS</sub> = -25V, V <sub>GS</sub> = 0V f = 1.0MHz
Output Capacitance	Coss		18	25	pF	
Reverse Transfer Capacitance	C <sub>rss</sub>	_	5	15		
Turn-On Delay Time (Note 11)	t <sub>d(on)</sub>	_	8	15		V <sub>DD</sub> = -50V, I <sub>D</sub> = -250mA V <sub>GEN</sub> = -10V
Rise Time (Note 11)	t <sub>f</sub>	_	8	15	no	
Turn-Off Delay Time (Note 11)	t <sub>d(off)</sub>		26	40	ns	
Fall Time (Note 11)	t <sub>f</sub>	_	20	30		

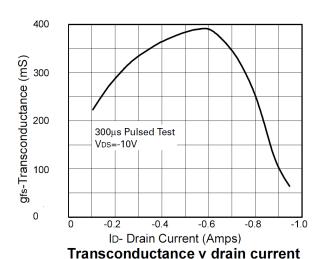
Notes:

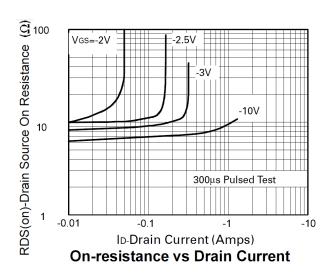
- 10. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
  11. Switching characteristics are independent of operating junction temperature.
  12. For design aid only, not subject to production testing.

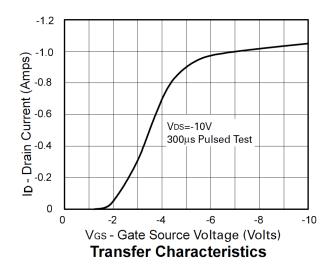


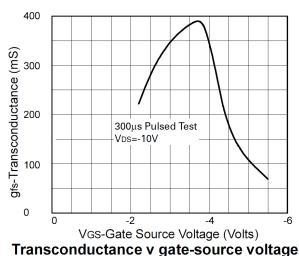
## **Typical Characteristics**

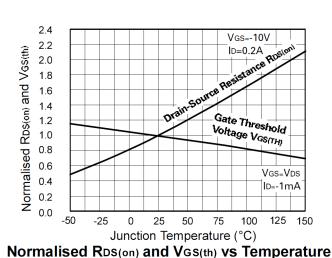








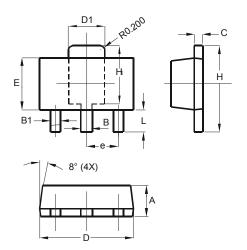






### **Package Outline Dimensions**

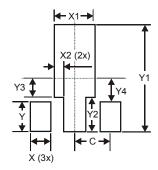
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
С	0.35	0.44		
D	4.40	4.60		
D1	1.62	1.83		
E	2.29	2.60		
е	1.50 Typ			
Н	3.94	4.25		
H1	2.63	2.93		
L	0.89	1.20		
All Dimensions in mm				

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Υ	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
С	1.500





December 2012

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